Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP LP2475w</th>
</tr>
</thead>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>9</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. External electric cables disconnecting process
2. Take off the stand ass’y and remove quick release
3. Remove rear cover
4. Remove shield and USB board
5. Remove front bezel and remove keyboard
6. Take 4 pcs screws off, disconnect 2 pcs cables and remove main frame ass’y
7. Take screws off main board, power board, remove main frame cover.
8. Take screws off and disassemble the stand ass’y
9. Take screws off and disassemble the stand ass’y
10. Disassemble the hinge ass’y
11. Disassemble the base ass’y

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP L2475W disassembly SOP

From: YiQuan.Kang
Date: APR-09-08
1. External electric cables disconnecting process

1. Disconnecting cable from back cover

External electric cables
2. Take off the stand ass’y and remove quick release

1. Remove the stand ass’y.

2. Take 4 pcs screws off the rear cover and remove the quick release.
3. Remove rear cover

1. Remove rear cover.
4. Remove shield and USB board

1. Take 1 pcs screw off and remove shield

2. Remove USB board

USB board

Shield
5. Remove front bezel and remove keyboard

1. Take off the 2 pcs tape.

1. Disconnect the FFC cable.

2. Remove the front bezel.

3. Remove the keyboard
6. Take 4 pcs screws off, disconnect 2 pcs cables and remove main frame ass’y.

1. Take off 4 pcs screws.

2. Disconnect 2 pcs cables.
7. Take screws off main board, power board, remove main frame cover.

1. Take 6 pcs screws off

2. Take 9 pcs screws off

Main board
Power board
Main frame cover
Insulate sheet
8. Take screws off and disassemble the stand ass’y.
9. Take screws off and disassemble the stand ass’y.
10. Disassemble the hinge ass’y

1. Disassemble hinge ass’y

External electric cables
11. Disassemble the base ass’y

1. Disassemble base ass’y